

OCP Engineering Workshop 25 September 2017 Dallas, TX

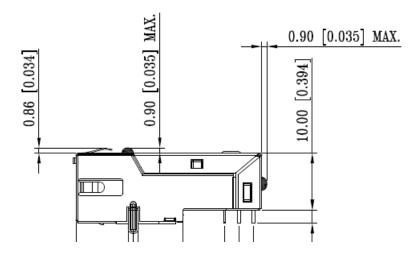
OCP Engineering Workshop – 25 September 2017 – Dallas, TX OCP NIC 3.0 Dell EMC Update Jon Lewis **Distinguished Engineer** 

# Agenda

- Form Factor Update
- Pinout:
  - Proposed changes to some pins/features
  - Pinout proposal for Connector A and B
- Closing thoughts

### Form Factor

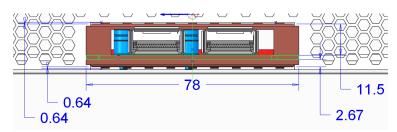
- Enumeration 14: 76 mm x 115 mm
- Top-side keepout: 11.0 mm
- Bottom-side keepout: 2.25 mm < x < 2.67 mm</li>
  - Really need the NIC vendors to finalize this number.
- Motherboard Thickness: Agree with 0.062", 0.076" and 0.093" +/- 10% tolerances.
  - Allows a wide range of layer counts and materials to be supported.
- Connector A = SFF-TA-1002 style 168 pin straddle mount connector.
- Connector B → Proposing 140 pin to allow a full x16.
- RJ-45 connectors should be mid-plane mounted. (3D models available)
  - 1x1 max top side height is 8.8 mm
  - 1x4 max top side height is 10.0 mm

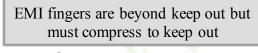


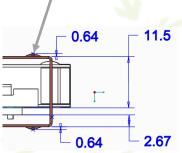
## Faceplate Spec Definition

- Dell prefers design similar to the design shown:
  - Enables EMI solution on card.
  - Enables convenient space for latching.
  - Minimizes vertical stack.
- Design intent and spec details:
  - Top/Bottom fold over and are inserted into the chassis.
  - Left/Right side EMI seal flush against rear wall.
  - EMI fingers need to compress to be flush with top/bottom flanges.
  - Proposal gives flexibility for different connectors.
- Open Items, in order:
  - Do we need to protect the entire underside of card for installation?
  - Retention mechanism selection and definition (internal/external/both?)
    - Options for latching could include 1/4 turn retention.
  - Should EMI fingers be on card or designed into chassis?
  - Do we need to specify LED locations, definitions, ...?



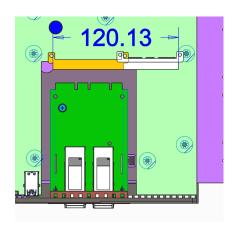


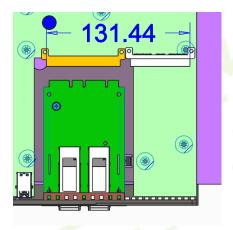




### Wider Card Consideration

- For the wider board Dell EMC would like to see the board grow to the right instead of the left.
  - Prefer a x16 on the additional section
  - Grow width to support additional 140 pin
- Top picture: Single connector instead of 2 connectors. Not sure if this is possible but would represent the minimum width for a wider card = ~127mm.
- Bottom picture: Connector B = 140 pins from the current concept models for the connector suppliers. The would make the card ~138mm.

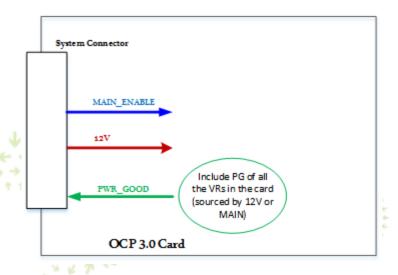


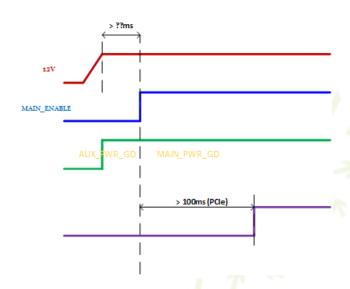


## **Proposed Pinout Description**

#### Power

- Repurpose the 12VAUX pins
- = 6 12V pins ~= 79W which should be sufficient (assume 1.1A per pin)
- MAIN\_EN: Signal from System to NIC indicating main power available.
- PWR GOOD: Signal from NIC to System indicating VRs are operating nominally.
  - Indudes all NIC rails.



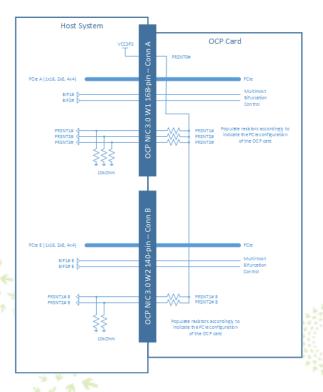


### Pinout - continued

- Deprecate CLK\_REQ
- Systems Management:
  - One SMBus
    - Includes FRU and temp sensor
  - One NC-SIRBT bus (including arbitration pins)
  - Add at least one "addressing" pin to enable dual OCP NIC 3.0 on the same management bus: SLOT\_ID
    - I2C address changed
    - NC-SI package ID changed (This assumes that the maximum number of OCP NIC 3.0 cards on a bus is 2. Additional addressing pins would be necessary if that increased.)
- Multi-Host: For Gen4/5 PCIe x4 ports seem to be an optimal choice
  - 4 x {PERST#, WAKE#, REFCLK}
    - REFCLK likely still required prior to Gen 5 PCle!
- Connector B: (140 pin to include x16)
  - 12V pins 5 additional pins to increase power to ~145W (nominal assuming 1.1A per pin)
  - Multi-host support (4 sets of PERST#, WAKE#, REFCLK)

## Pinout - continued

- Presence/Bifurcation
  - Dual-purpose the existing 3 presence pins and add 2 pins (BIFn#).
    - Allows for bidirectional bifurcation



#### Multi-host Bifurcation (from Host to OCP card)

W1 Conn A		W2 Conn B		Host Root Port Configuration	
BIF1#	BIF2#	BIF1#B	BIF2#B	Bus A	Bus B
0	0	0		x16	x16
1	0	0		2 x8	2 x8
0	1	0		4 x4	4 x4
1	1	0		x16	2 x8
0	0	1		x16	4 x4
1	0	1		2 x8	x16
0	1	1		2 x8	4 x4
1	1	1		4 x4	x16
				4 x4	2 x8

#### Root Port Bifurcation (from OCP card to Host)

W1 Conn A			W2 Conn B		Conn A End	Conn B End	
PRSNT3#	PRSNT2#	PRSNT1#	PRSNT2# B	PRSNT1#B	Device Config	Device Config	
RFU	0	0	0	0	Not present	Not present	
RFU	0	1	0	0	x16	Not present	
RFU	1	0	0	0	2 x8	Not present	
RFU	1	1	0	0	RFU	Not present	
RFU	0	1	0	1	x16	x16	
RFU	1	0	0	1	2 x8	x16	
RFU	1	1	0	1	RFU	x16	
RFU	0	1	1	0	x16	2 x8	
RFU	1	0	1	0	2 x8	2 x8	
RFU	1	1	1	0	RFU	2 x8	
RFU	0	1	1	1	x16	RFU	
RFU	1	0	1	1	2 x8	RFU	
RFU	1	1	1	1	x32		

Proposed pinout GND
PER<sub>b</sub>7
GND
PRSNT24
Key
GND H OCP x16 168 pin

## Closing Thoughts

- Given the current trajectory it would be nice to get together more frequently in targeted groups for discussions to close open items:
  - Mechanical: Faceplate, latching mechanism, ...
  - Pinout: definition of pins, new features, ...

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